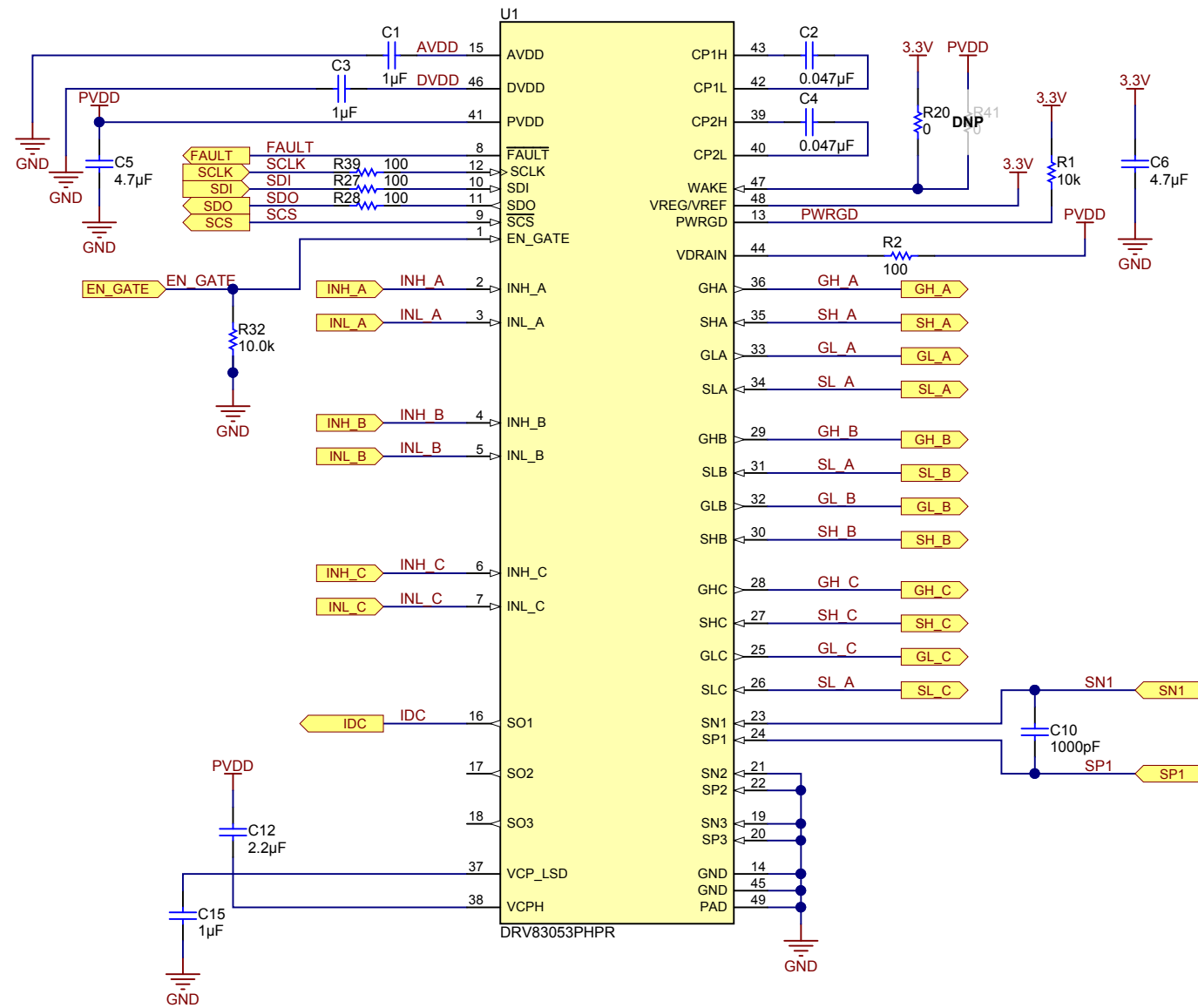


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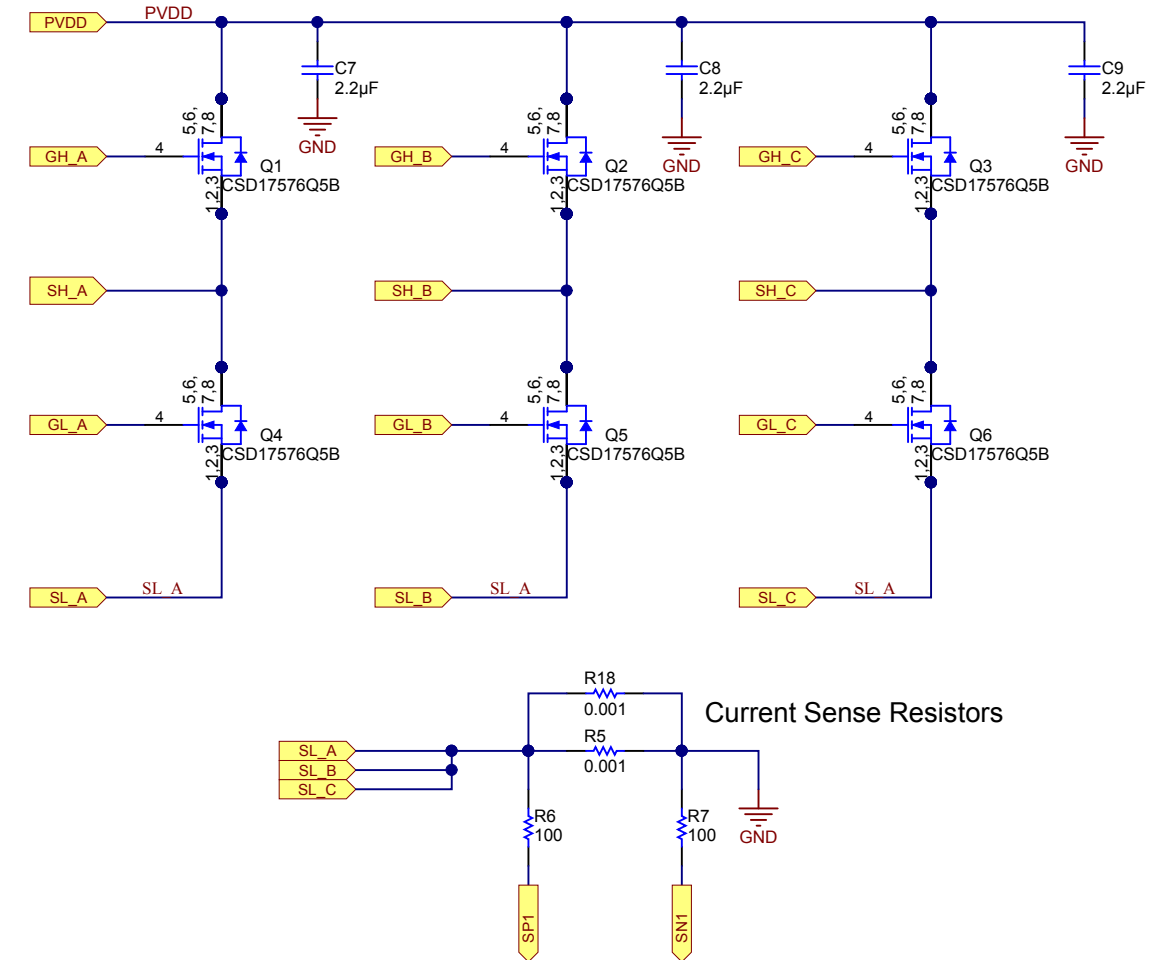
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SVN Rev: Version control disabled	Assembly Variant: 001	Project Title: 10.8V, 20A, High Efficiency BLDC Drive for Power	Sheet: 2 of 5
Drawn By:	File: Pg2-Blockdiagram.SchDoc	Size: B	
Engineer: Manu Balakrishnan	Contact: http://www.ti.com/support		



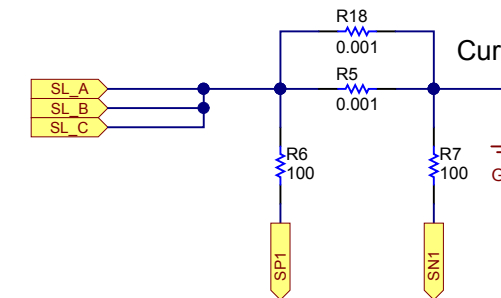
Three Phase gate Driver



Three Phase Inverter



Current Sense Resistors

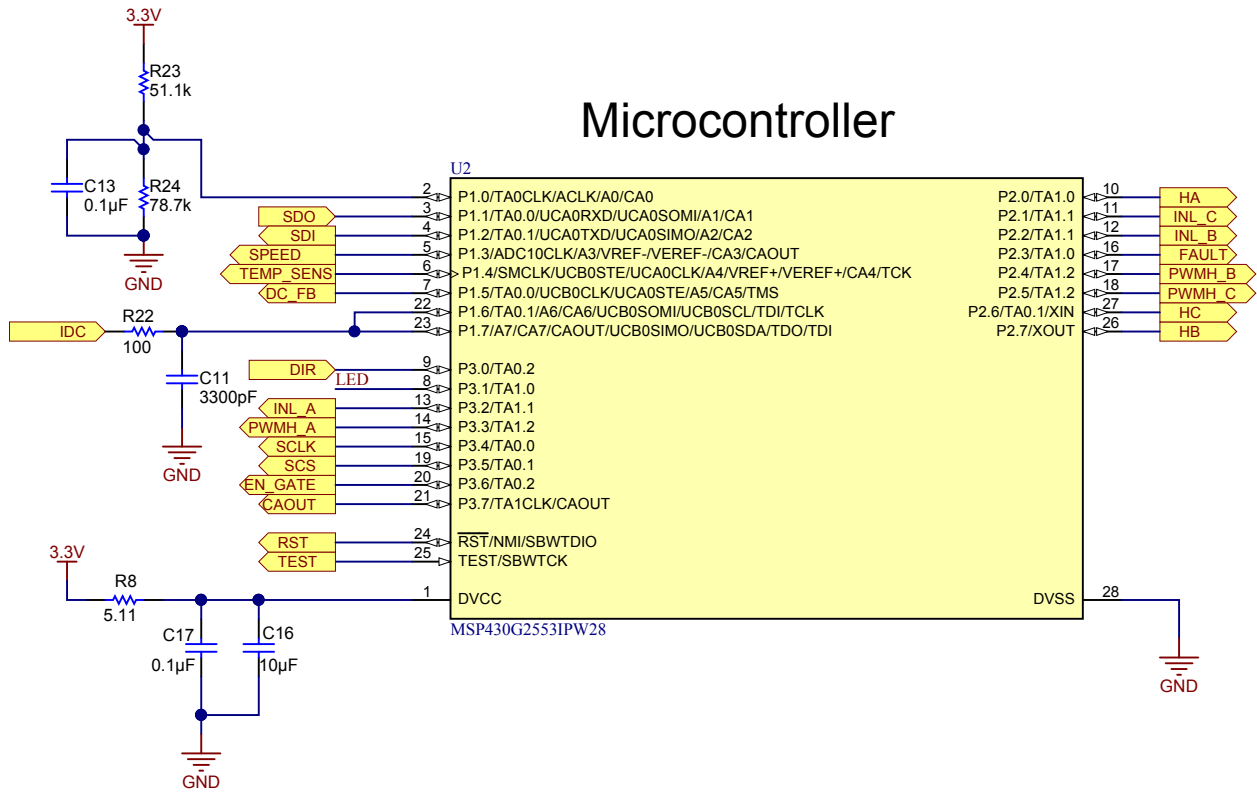


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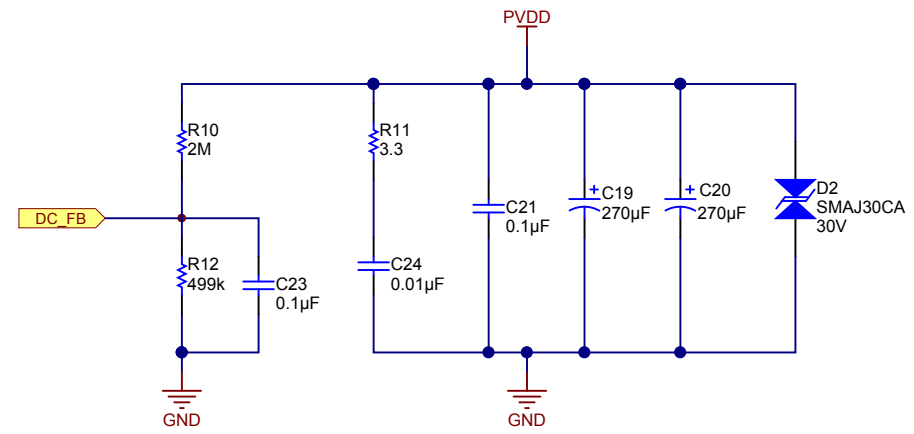
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Drawn By: Manu Balakrishnan	Assembly Variant: 001	Sheet: 3 of 5
Engineer: Manu Balakrishnan	File: pg3-Main.SchDoc	Size: B
	Contact: http://www.ti.com/support	



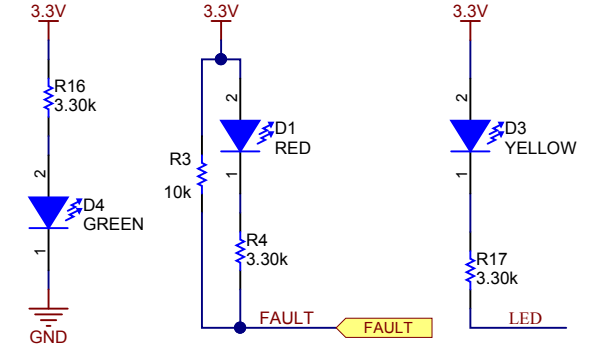
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Microcontroller



Power Supply



LED Indication

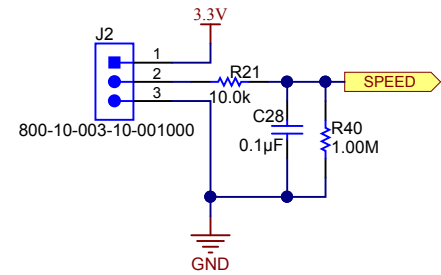
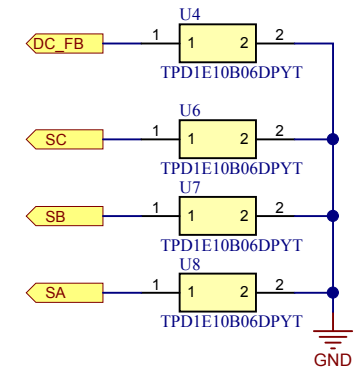
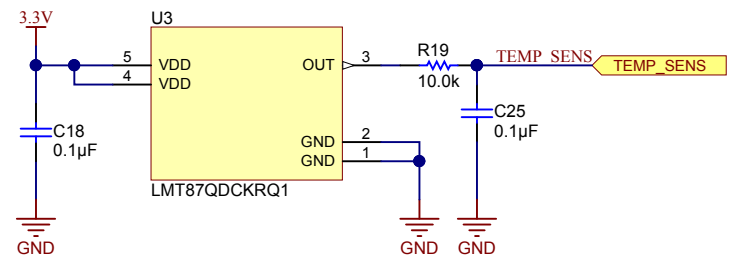
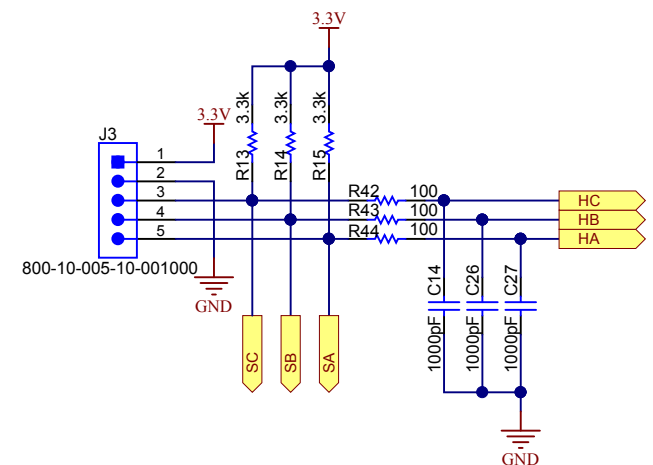
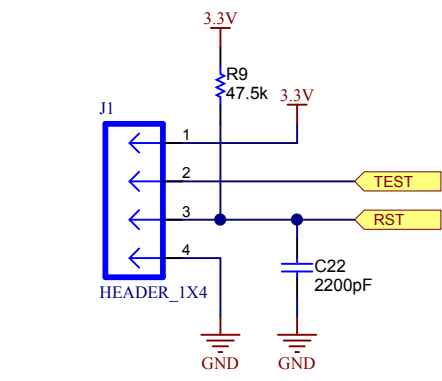
MCU Programming connector

Hall Sensor interface

Temperature Sensor

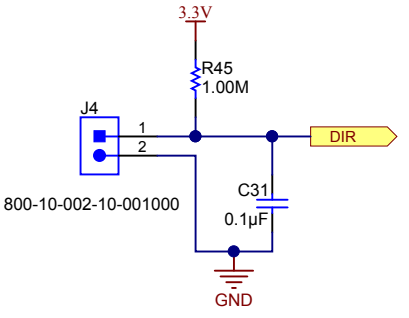
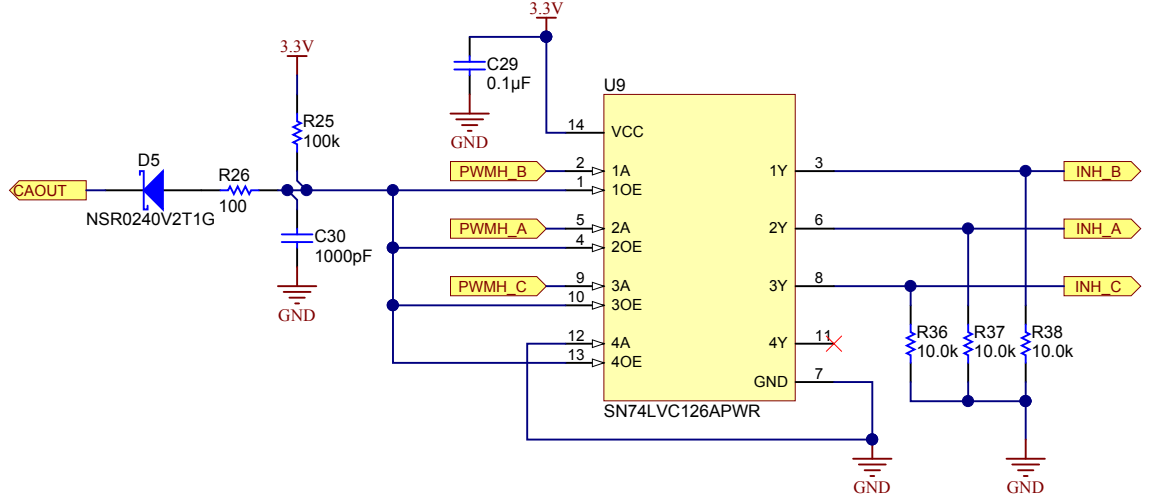
ESD Protection

SPEED Reference



Over Current Shutdown - Buffer

DIRECTION Change



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PCB Number: TIDA-00771
PCB Rev: E2

LBL1

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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